1-9. (CANCELED)

10. (NEW) A thermal conductive material comprising:

an unvulcanized organic material; and

a filler having a higher thermal conductivity than the unvulcanized organic material,

wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive material comes in contact.

11. (NEW) The thermal conductive material according to claim 10, wherein the thermal conductive material is plasticized at 60°C under a pressure equal to or above 6.0 $g/cm^2$.

12. (NEW) The thermal conductive material according to claim 10, wherein the unvulcanized organic material has a melting transition in the range of 30-70°C and a viscosity at 100°C is equal to or above 70,000cP, a weight ratio of the filler to the thermal conductive material is in the range of 30-90%.

13. (NEW) The thermal conductive material according to claim 10, wherein the thermal conductive material is in an elastomeric state at room temperature.

14. (NEW) The thermal conductive material according to claim 10, wherein the organic material is an olefin resin.

15. (NEW) The thermal conductive material according to claim 11, wherein the organic material is unvulcanized EPDM having a weight average molecular weight of between 7,000-50,000.

16. (NEW) The thermal conductive material according to claim 10, wherein the filler is at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber.

17. (NEW) The thermal conductive material according to claim 10, wherein the filler is a material serving as an electromagnetic shield.

18. (NEW) A method for producing a thermal conductive material comprising an organic material and a filler having higher thermal conductivity than the organic material, wherein the thermal conductive material is plasticized at least in the temperature range of 30-65°C and the thermal conductive material changes form

flexibly corresponding to a form of a surface of a member with which the thermal conductive material comes in contact, the method comprising the steps of:

kneading a filler and an organic material; and

molding the kneaded material.

19. (NEW) A thermal conductive material comprising:

an unvulcanized EPDM material having a weight average molecular weight of between 7,000-50,000; and

a filler having a higher thermal conductivity than the unvulcanized EPDM material,

wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive material comes in contact.